



JOCDA4AB-D8P/S Series

Rev.A.1.0

DESCRIPTION:

The products are gate driver opto-couplers in a plastic

3 11 5

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
LED	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	100	mW
Detector	Output Voltage	V_O	35	V
	Supply Voltage	V_{CC}	35	V
	Power Dissipation	P_C	400	mW
Isolation Voltage		V_{iso}	5000	Vrms
Operating Temperature		T_{opr}	-40~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Total Power Dissipation		P_{tot}	500	mW
Soldering Temperature		T_{sol}	260	

NOTE1: μ

NOTE2:

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10mA$	-	1.35	1.6	V
	Reverse Current	I_R	$V_R=6V$	-	-	1	μA
	Terminal Capacitance	C_t	$V=0, f=1MHz$	-	60	-	pF
Output	Peak High-level Output Current	I_{OPH}	$V_O=V_{CC}-4V$, Pulse width $\leq 50\mu s$	-1	-	-	A
			$V_O=V_{CC}-10V$, Pulse width $\leq 10\mu s$	-4	-	-	A
	Peak Low-level Output Current	I_{OPL}	$V_O=V_{EE}+2.5V$, Pulse width $\leq 50\mu s$	1	-	-	A
			$V_O=V_{EE}+10V$, Pulse width $\leq 10\mu s$	4	-	-	A
	High Level Supply Current	I_{CCH}	$I_F=10mA$ $R_g=10\Omega$, $C_g=25nF$	-	1.9	3	mA
	Low Level Supply Current	I_{CCL}	$V_F=0V$, $R_g=10\Omega$, $C_g=25nF$	-	1.9	3	mA

	High Level Output Voltage	V_{OH}	$I_O=-100mA$	$V_{CC}-0.3$	$V_{CC}-0.2$	-	V
	Low Level Output Voltage	V_{OL}	$I_O=100mA$	-	-	0.2	V
	Threshold Input Current	I_{FLH}	$V_O=5V$	-	1.2	5	mA
	Threshold Input Voltage	V_{FHL}	$V_O=5V$	0.8	-	-	V
	Supply Voltage	V_{CC}	-	15	-	30	V
	UVLO Threshold	VUVLO+	$V_O=5V$, $I_F=10mA$	12.1	12.8	13.5	V
		VUVLO-	$V_O=5V$, $I_F=10mA$	11.1	11.8	12.4	V

SWITCHING SPECIFICATION

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Propagation Delay Time to High Output Level	t_{PLH}	$R_g=10\Omega$, $C_g=25nF$, $f=20kHz$, Duty Cycle=50%, $I_F=7mA$, $V_{CC}=30V$	50	-	200	ns
Propagation Delay Time to Low Output Level	t_{PHL}		50	-	200	
Pulse Width Distortion	PWD		-	-	70	
Propagation Delay Difference Between Any Two Parts	$t_{PHL}-t_{PLH}$		-100	-	100	
Output Rise Time (10 to 90%)	t_r	$R_g=10\Omega$, $C_g=25nF$, $I_F=0 \rightarrow 7mA$, $V_{CC}=30V$	-	50	-	
Output Fall Time (90 to 10%)	t_f	$R_g=10\Omega$, $C_g=25nF$, $I_F=7 \rightarrow 0mA$, $V_{CC}=30V$	-	50	-	
Common Mode Transient Immunity at High Level Output	$ CM_H $	$I_F=7mA$ $V_{CC}=30V$, $T_a=25^\circ C$, $V_O(min)=26V$ $V_{CM}=1500V_{pp}$	± 35	-	-	kV/ μs
Common Mode Transient Immunity at Low Level Output	$ CM_L $	$I_F=0mA$ $V_{CC}=30V$, $T_a=25^\circ C$, $V_O(max)=1V$ $V_{CM}=1500V_{pp}$	± 35	-	-	kV/ μs

Note1

Note2

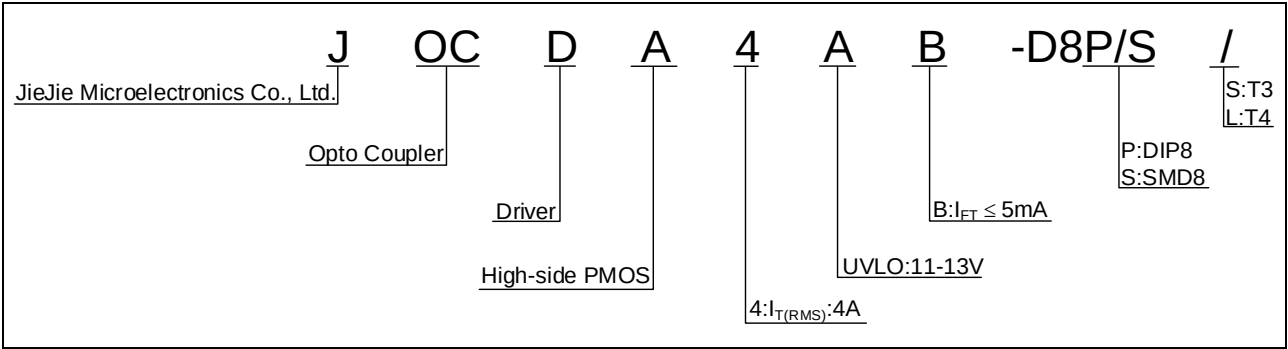
Note3

Recommended Operating Conditions

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Input On-state Current	$I_{F(ON)}$	7	-	10	mA
Input Off-state Voltage	$V_{F(OFF)}$	0	-	0.8	V
Supply Voltage	V_{CC}	15	-	30	V
Operating Frequency	f	-	-	50	kHz

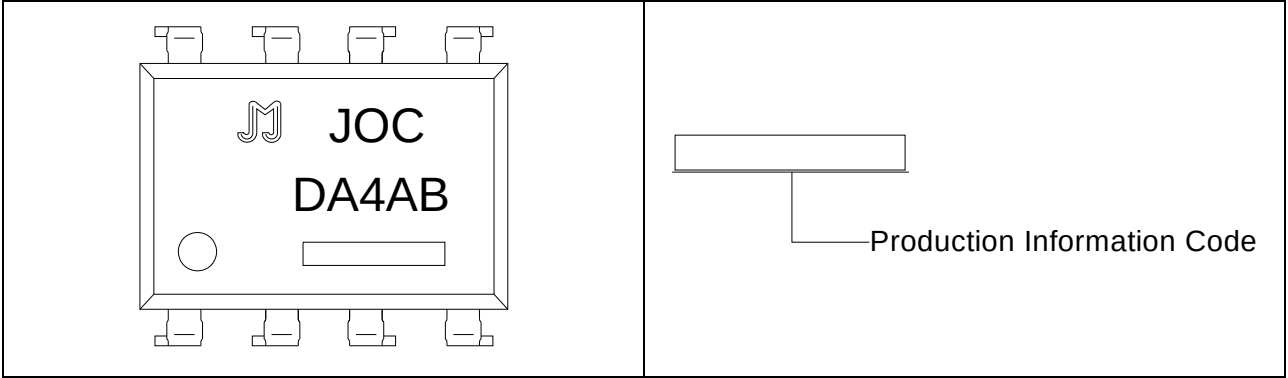
Note1**Note2****Note3****Note4**

ORDERING INFORMATION



Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box

MARKING



Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

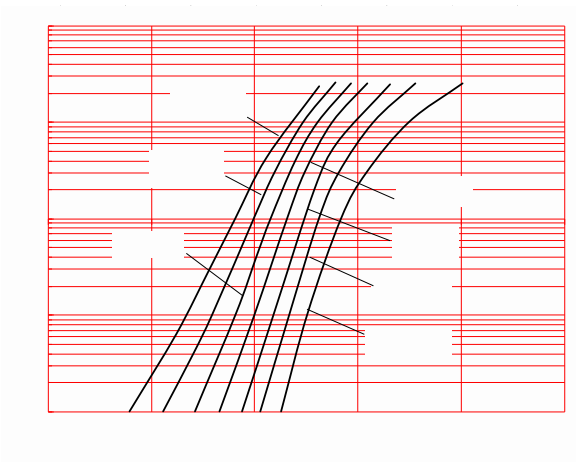


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

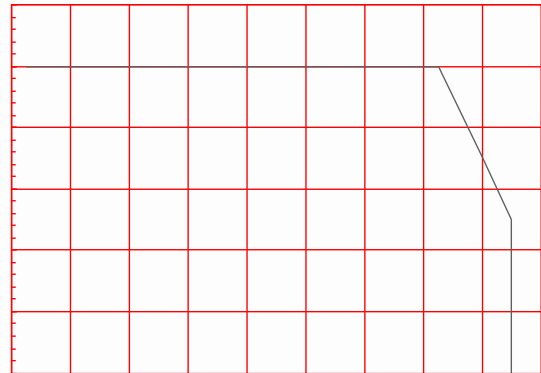


FIG.3: Collector Power Dissipation vs. Ambient Temperature

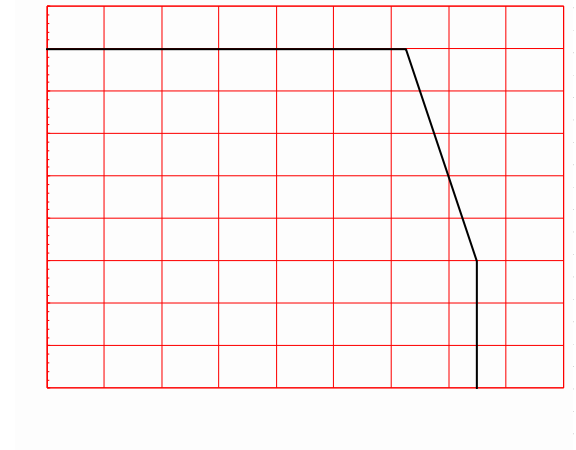


FIG.4: Threshold Input Current vs. Ambient Temperature



FIG.5: Low-level Supply Current vs. Ambient Temperature

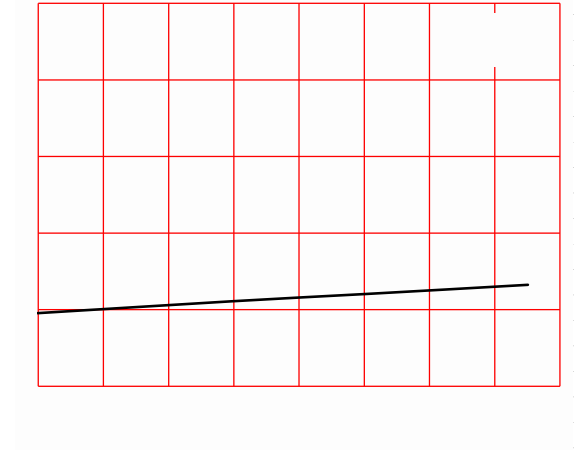


FIG.6: High-level Supply Current vs. Ambient Temperature

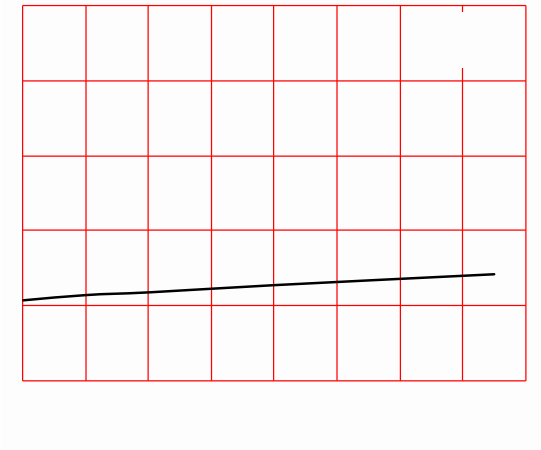


FIG.7: Low-level Output Voltage vs. Ambient Temperature

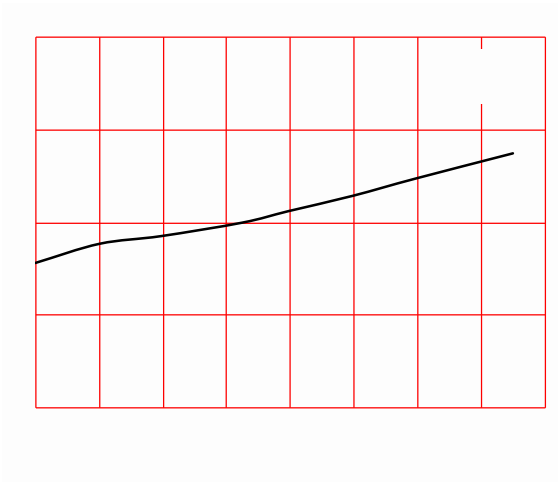


FIG.8: High-level Output Voltage vs. Ambient Temperature

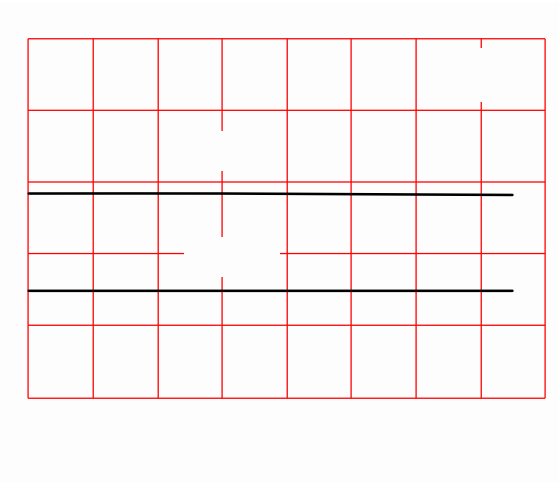


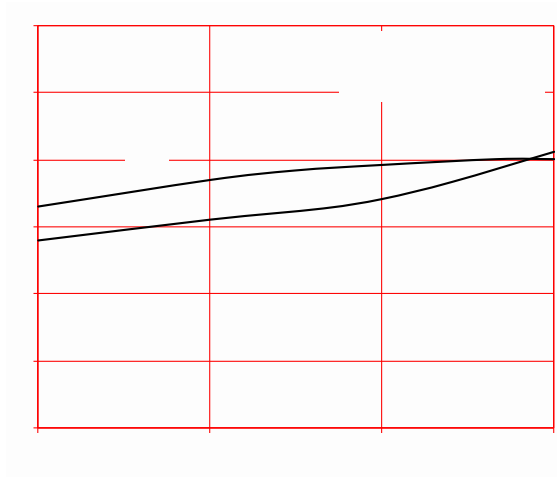
FIG.9: Peak Low-level Output Current vs. Low-level Output Voltage



FIG.10: High-level Output Voltage Drop vs. Ambient Temperature



FIG.13: Propagation Delay Time vs. Supply Voltage



Test Circuits

FIG.14: Switching Time Test Circuit and Waveform

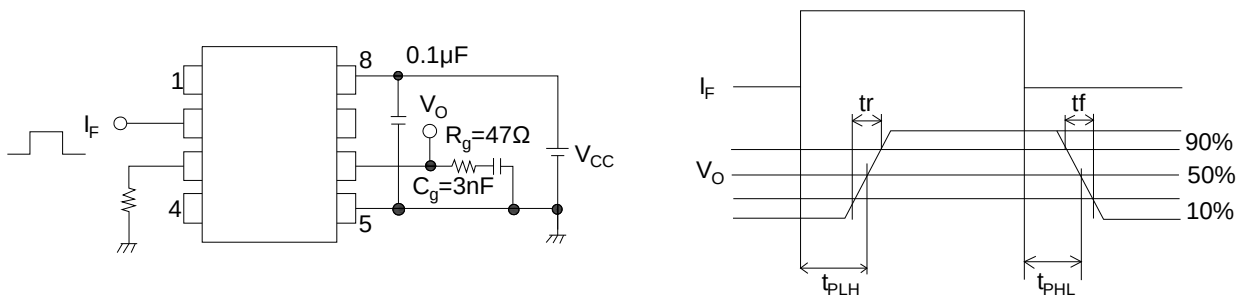
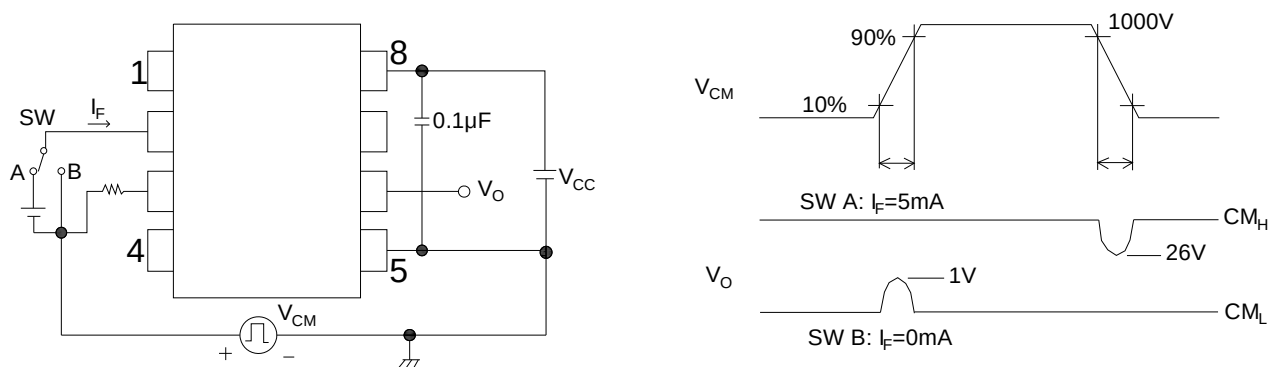
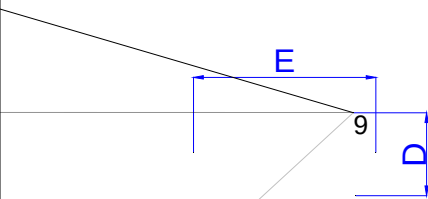


FIG.15: Common-Mode Transient Immunity Test Circuit and Waveform



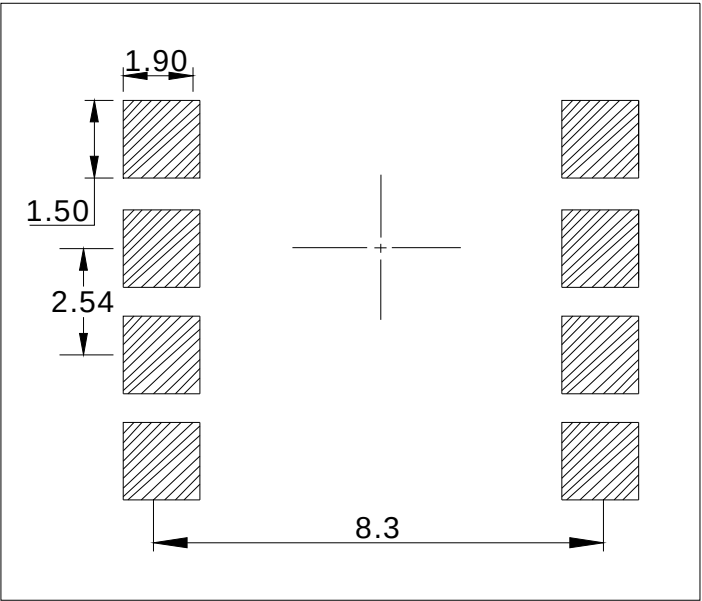
Package Dimension (Unit: mm)

Standard DIP Type:



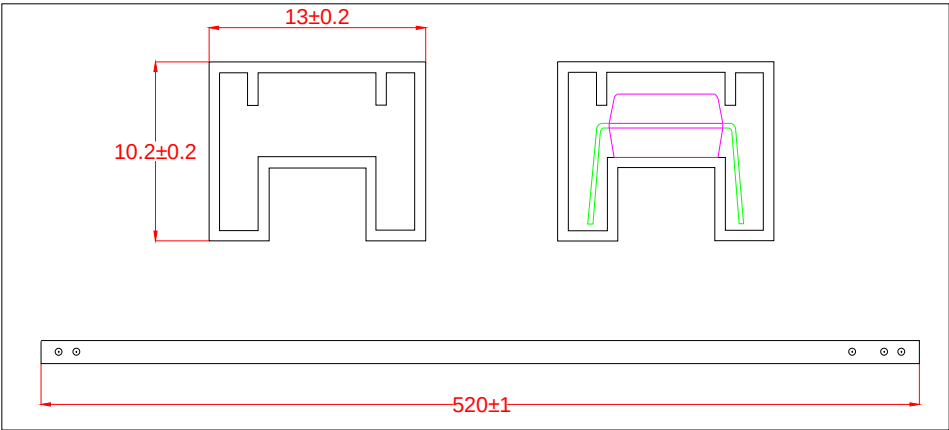
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A						
B	0.5	0.75	1.0	0.020	0.030	0.040

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



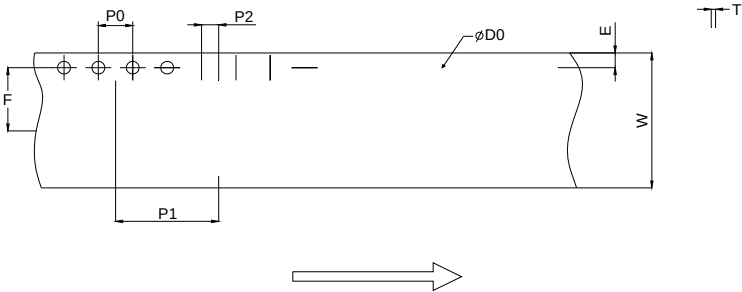
TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP



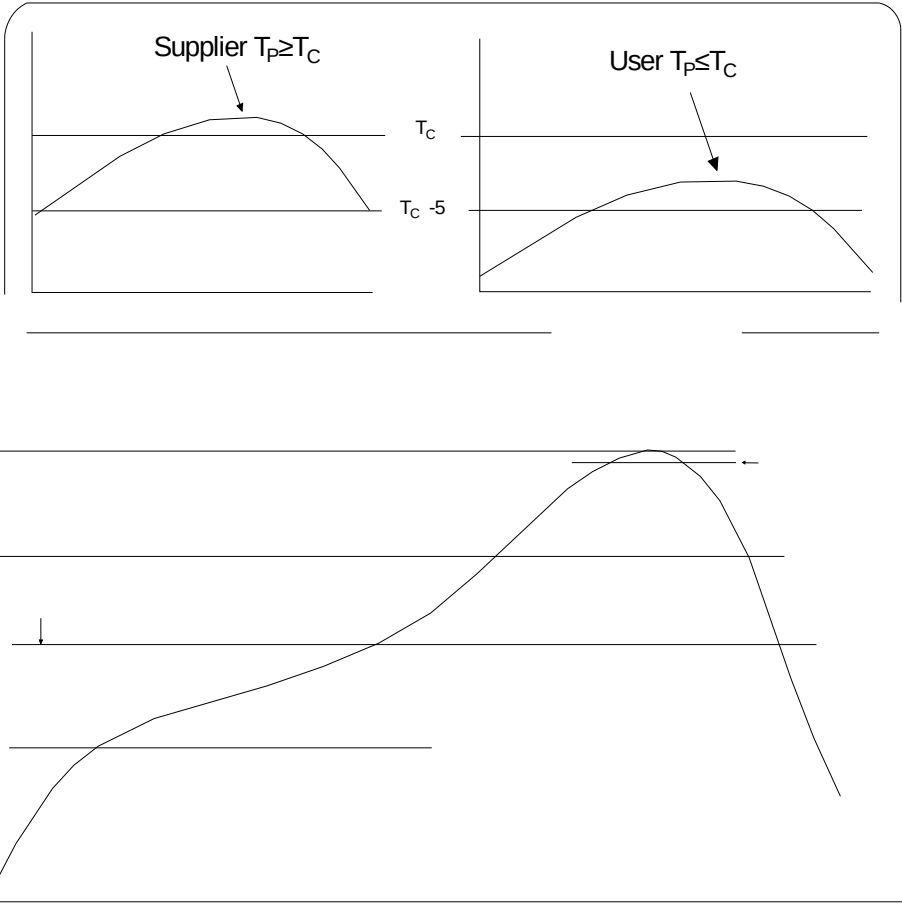
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S

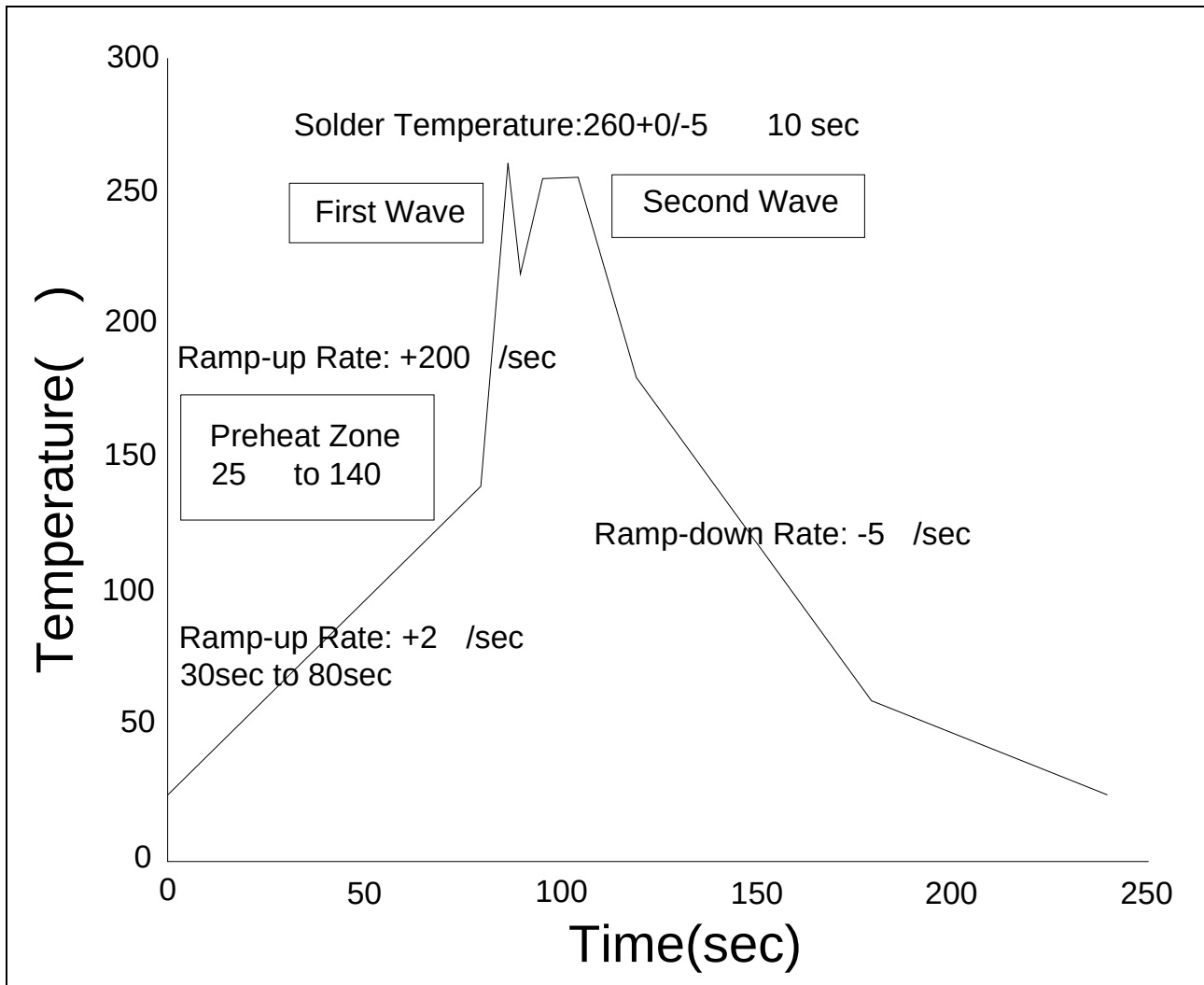


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638

REFLOW INFORMATION



WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360 ± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures.